## **CLAIMS**

## What is claimed is:

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1. A method comprising:

forming a thin flexible substrate having a conductor region adapted to mount an integrated circuit;

mount an integrated eneur,

forming a plurality of traces in the conductor region; and forming a plurality of lands coupled to the traces.



- 1 2. The method regited in claim 1, wherein the substrate is formed of material
- 2 from the group comprising a polymeric film, polyimide, polyester, polyparabanic
- 3 acid, epoxy, and fiberglass.
- 1 3. The method regited in claim 1, wherein forming the substrate comprises
- 2 forming a plurality of layers, each comprising a plurality of traces in the conductor
- 3 region.
- 1 4. The method recited in claim 1, wherein forming the substrate comprises
- 2 forming a plurality of sprocket holes outside the conductor region.
- 1 5. The method recited in claim 1, wherein the lands are arranged in a ball grid
- 2 array, the method further comprising:
- forming solder balls on the plurality of lands.



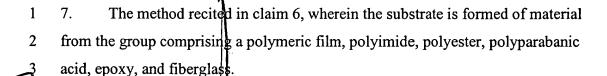
A method comprising:

- 2 forming a thir, flexible substrate having a conductor region comprising a
- 3 plurality of traces and a plurality of lands coupled to the plurality of traces; and
- 4 coupling pads on an integrated circuit (IC) to corresponding lands on the
- 5 substrate.

Attorney Docket No. 884.469US1

Client Reference No. P11299

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- 8. The method recited in claim 6, wherein forming the substrate comprises forming a plurality of layers, each comprising a plurality of traces in the conductor region.
- 1 9. The method recited in claim 6, wherein forming the substrate comprises
- 2 forming a plurality of sprocket holes outside the conductor region.
- 1 10. The method regited in claim 6 and further comprising before coupling:
- 2 forming solder balls on the lands.
- 1 11. The method recited in claim 6 and further comprising:
- 2 mounting the substrate on an additional substrate.
- 1 12. The method recited in claim 11, wherein the additional substrate comprises
- 2 a printed circuit board.
- 1 13. The method recited in claim 11, wherein lands are coupled to corresponding
- 2 terminals on the additional substrate.
- 1 14. The method recited in claim 12 and further comprising before mounting:
- 2 forming solder balls on the lands.
- 1 15. The method recited in claim 12, wherein the lands are coupled to the
- 2 terminals using a ball grid array.

Attorney Docket No. 884.469US1

Client Reference No. P11299

16. The method redited in claim 12, wherein leads are coupled between corresponding lands and terminals.

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17, An electronic package substrate comprising:

a thin, flexible, electrically insulating film having a conductor region

adapted to mount an integrated circuit;

a plurality of traces in the conductor region; and

a plurality of lands coupled to the traces.

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18. The electronic package substrate recited in claim 17, wherein the film is formed of material from the group comprising a polymeric film, polyimide, polyester, polyparabanic acid, epoxy, and fiberglass.

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The electronic package substrate recited in claim 17, wherein the film 19. comprises a plurality of layers, each comprising a plurality of traces in the conductor region.

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The electronic package substrate recited in claim 17, wherein the lands are .20. arranged in a ball grid array.

21. An electronic package comprising:

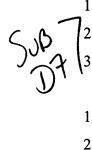
an electrically insulating film having a thickness in the range of approximately .15 to .90 millimeters, the film having a conductor region, a plurality of traces in the conductor region, and a plurality of lands coupled to the traces; and

an electronic component having a plurality of pads coupled to the plurality

6 of lands.

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22. The electronic package recited in claim 21, wherein the film is formed of material from the group comprising a polymeric film, polyimide, polyester, polyparabanic acid, epoxy, and fiberglass.

23. The electronic package recited in claim 21, wherein the film comprises a plurality of layers, each comprising a plurality of traces in the conductor region, and

wherein each layer has a thickness within the range of approximately .15 to .30

4 millimeters.

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1 24. The electronic package recited in claim 21, wherein the lands are arranged in

2 a ball grid array.

1 25. The electronic package recited in claim 21, wherein the electronic component comprises an integrated circuit.

26. An electronic system comprising at least one electronic assembly comprising:

a thin, flexible, electrically insulating film having a conductor region, a plurality of traces in the conductor region, and a plurality of lands coupled to the traces; and

an electronic component having a plurality of pads coupled to the plurality of lands.

SUB 72 DA 73 27. The electronic system recited in claim 26, wherein the film is formed of material from the group comprising a polymeric film, polyimide, polyester, polyparabanic acid, epoxy, and fiberglass.

28. The electronic system recited in claim 26, wherein the film comprises a plurality of layers, each comprising a plurality of traces in the conductor region.

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	1	30. The electronic system recited in claim 26, wherein the electronic component
	2	comprises an integrated circuit.
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	$\sqrt{\chi}^1$	A data processing system comprising:
35	$\int 2$	\ a bus coupling components in the data processing system;
r,	1 3	a display coupled to the bus;
	4	a memory coupled to the bus; and
	5	a processor coupled to the bus and comprising an electronic assembly
13	6	including,
	7	a thin, flexible electrically insulating film having a conductor region,
Ö	8	a plurality of traces in the conductor region, and a plurality of lands coupled
11	9	to the traces; and
IJ	10	an integrated circuit having a plurality of pads coupled to the
:	11	plurality of lands.
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A dies dem ent [m]	1	32. The data processing system recited in claim 31, wherein the film is formed
N II/	2 27	of material from the group comprising a polymeric film, polyimide, polyester,
	)	polyparabanic acid, epoxy, and fiberglass.
J	ד יע	perspendicular detay openas, and needstates.
	1	The data processing system recited in claim 31, wherein the film comprises
	ì	
	۷	plurality of layers, each comprising a plurality of traces in the conductor region.
	1	34. The data processing system recited in claim 31, wherein the lands are
	. 2	arranged in a ball grid array.
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The electronic system recited in claim 26, wherein the lands are arranged in

Attorney Docket No. 884.469US1

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a ball grid array.

Client Reference No. P11299